NC7WZ07

TinyLogic UHS Dual Buffer (Open-Drain Outputs)

ON Semiconductor®

www.onsemi.com

Description

The NC7WZ07 is a dual buffer with open−drain outputs from ON Semiconductor's Ultra−High Speed (UHS) series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra−high speed with high output drive, while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over a very broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} range. The inputs and outputs are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating voltage.

Features

- Ultra−High Speed: t_{PZL} 2.3 ns (Typical)
- High I_{OL} Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.50 V
- Power Down High−Impedance Inputs / Outputs
- Over−Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra−Small MicroPak™ Packages
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

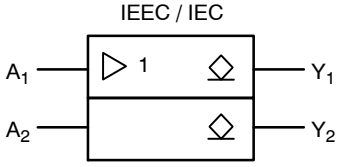
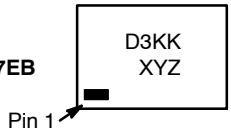


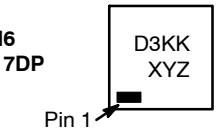
Figure 1. Logic Symbol

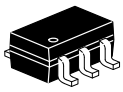
MARKING DIAGRAMS

SIP6
CASE 127EB

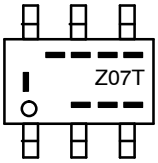


UDFN6
CASE 517DP





SC−88
CASE 419AD−01



D3, Z07	= Specific Device Code
KK	= 2−Digit Lot Run Traceability Code
XY	= 2−Digit Date Code Format
Z	= Assembly Plant Code
▬▬▬	= Year Coding Scheme
▮▪▬	= Plant Code Identifier
T	= Die Run Code
▬▬	= Eight−Week Datacoding Scheme

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

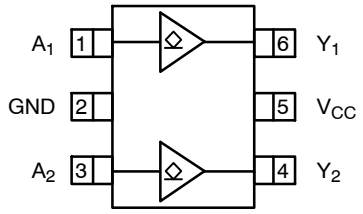


Figure 2. SC−88 (Top View)

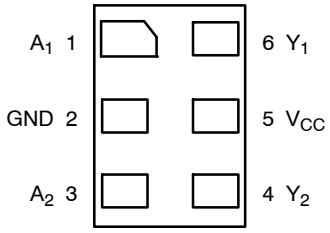
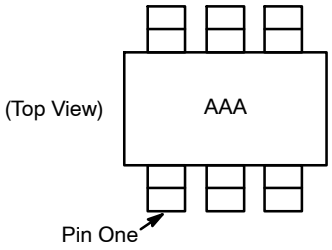


Figure 3. MicroPak (Top Through View)



NOTES:
1. AAA represents product code top mark *(see Ordering Information)*.
2. Orientation of top mark determines pin one location.
3. Read the top mark left to right, pin one is the lower left pin.

Figure 4. Pin 1 Orientation

PIN DEFINITIONS

Pin # SC−88	Pin # MicroPak	Name	Description
1	1	A_1	Input
2	2	GND	Ground
3	3	A_2	Input
4	4	Y_2	Output
5	5	V_{CC}	Supply Voltage
6	6	Y_1	Output

FUNCTION TABLE (Y = A)

Inputs	Output
A	**Y**
LOW Logic Level	LOW Logic Level
HIGH Logic Level	HIGH Impedance Output State, Open Drain

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage		−0.5	6.5	V
V_{IN}	DC Input Voltage		−0.5	6.5	V
V_{OUT}	DC Output Voltage		−0.5	6.5	V
I_{IK}	DC Input Diode Current	V_{IN} < −0.5 V	−	−50	mA
I_{OK}	DC Output Diode Current	V_{OUT} < −0.5 V	−	−50	mA
I_{OUT}	DC Output Current		−	±50	mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current		−	±100	mA
T_{STG}	Storage Temperature Range		−65	+150	°C
T_J	Junction Temperature Under Bias		−	+150	°C
T_L	Junction Lead Temperature (Soldering, 10 Seconds)		−	+260	°C
P_D	Power Dissipation in Still Air	SC−88−6	−	190	mW
		MicroPak−6	−	327	
		MicroPak2™−6	−	327	
ESD	Human Body Model, JEDEC: JESD22−A114		−	4000	V
	Charge Device Model, JEDEC: JESD22−C101		−	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.5	5.5	
V_{IN}	Input Voltage		0	5.5	V
V_{OUT}	Output Voltage		0	5.5	V
t_r, t_f	Input Rise and Fall Times	V_{CC} at 1.8 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V_{CC} at 3.3 V ±0.3 V	0	10	
		V_{CC} at 5.0 V ±0.5 V	0	5	
T_A	Operating Temperature		−40	+85	°C
θ_{JA}	Thermal Resistance	SC−88−6	−	659	°C/W
		MicroPak−6	−	382	
		MicroPak2−6	−	382	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must be held HIGH or LOW. They may not float.

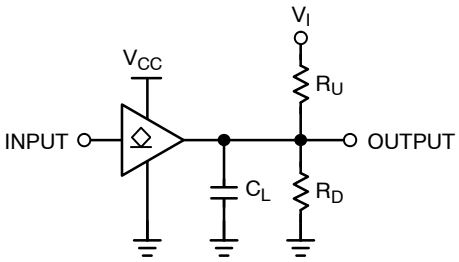
DC ELECTICAL CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C			T_A = −40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	HIGH Level Input Voltage	1.65 to 1.95		0.65 V_{CC}	–	–	0.65 V_{CC}	–	V
		2.30 to 5.50		0.70 V_{CC}	–	–	0.70 V_{CC}	–	
V_{IL}	LOW Level Input Voltage	1.65 to 1.95		–	–	0.35 V_{CC}	–	0.35 V_{CC}	V
		2.30 to 5.50		–	–	0.30 V_{CC}	–	0.30 V_{CC}	
I_{LKG}	HIGH Level Output Leakage Current	1.65 to 1.95	V_{IN} = V_{IH}, V_{OUT} = V_{CC} or GND	–	–	±5	–	±10	μA
V_{OL}	LOW Level Output Voltage	1.65	V_{IN} = V_{IL}, I_{OL} = 100 μA	–	0.00	0.10	–	0.00	V
		1.80		–	0.00	0.10	–	0.10	
		2.30		–	0.00	0.10	–	0.10	
		3.00		–	0.00	0.10	–	0.10	
		4.50		–	0.00	0.10	–	0.10	
		1.65	I_{OL} = 4 mA	–	0.80	0.24	–	0.24	
		2.30	I_{OL} = 8 mA	–	0.10	0.30	–	0.30	
		3.00	I_{OL} = 16 mA	–	0.16	0.40	–	0.40	
		3.00	I_{OL} = 24 mA	–	0.24	0.55	–	0.55	
		4.50	I_{OL} = 32 mA	–	0.25	0.55	–	0.55	
I_{IN}	Input Leakage Current	1.65 to 5.5	0 ≤ V_{IN} ≤ 5.5 V	–	–	±0.1	–	±10	μA
I_{OFF}	Power Off Leakage Current	0	V_{IN} or V_{OUT} = 5.5 V	–	–	1	–	10	μA
I_{CC}	Quiescent Supply Current	1.65 to 5.50	V_{IN} = 5.5 V, GND	–	–	1	–	10	μA

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C			T_A = −40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
t_{PZL}, t_{PLZ}	Propagation Delay (Figure 5, 6)	1.65	C_L = 50 pF, RU = 500 Ω, RD = 500 Ω, V_I = 2 x V_{CC}	–	6.6	11.5	–	12.6	ns
		1.80		–	5.5	9.5	–	10.5	
		2.50 ±0.20		–	3.7	5.8	–	6.4	
		3.30 ±0.30		–	2.9	4.4	–	4.8	
		5.00 ±0.50		–	2.3	3.5	–	3.9	
		1.65	C_L = 50 pF, RU = 500 Ω, RD = 500 Ω, V_I = 2 x V_{CC}	–	5.5	11.5	–	12.6	
		1.80		–	4.3	9.5	–	10.5	
		2.50 ±0.20		–	2.8	5.8	–	6.4	
		3.30 ±0.30		–	2.1	4.4	–	4.8	
		5.00 ±0.50		–	1.4	3.5	–	3.9	
C_{IN}	Input Capacitance	0		–	2.5	–	–	–	pF
C_{OUT}	Output Capacitance	0		–	4.0	–	–	–	pF
C_{PD}	Power Dissipation Capacitance (Note 5) (Figure 7)	3.30		–	3	–	–	–	pF
		5.00		–	4	–	–	–	

5. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).



NOTE:
6. C_L includes load and stray capacitance.
7. Input PRR = 1.0 MHz, t_W = 500 ns.

Figure 5. AC Test Circuit

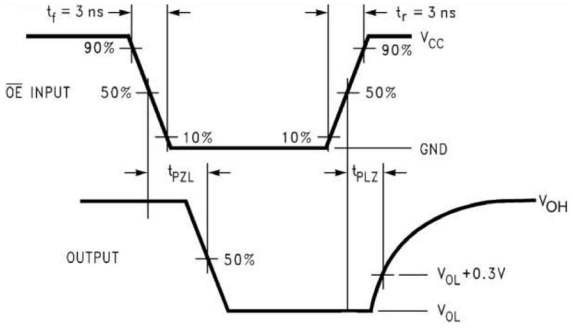
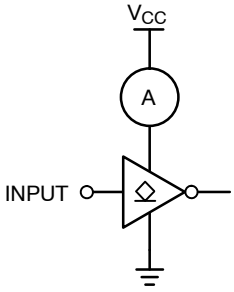


Figure 6. AC Waveforms



NOTE:
8. Input = AC Waveform; $t_r = t_f$ = 1.8 ns; PRR = Variable; Duty Cycle = 50%.

Figure 7. I_{CCD} Test Circuit

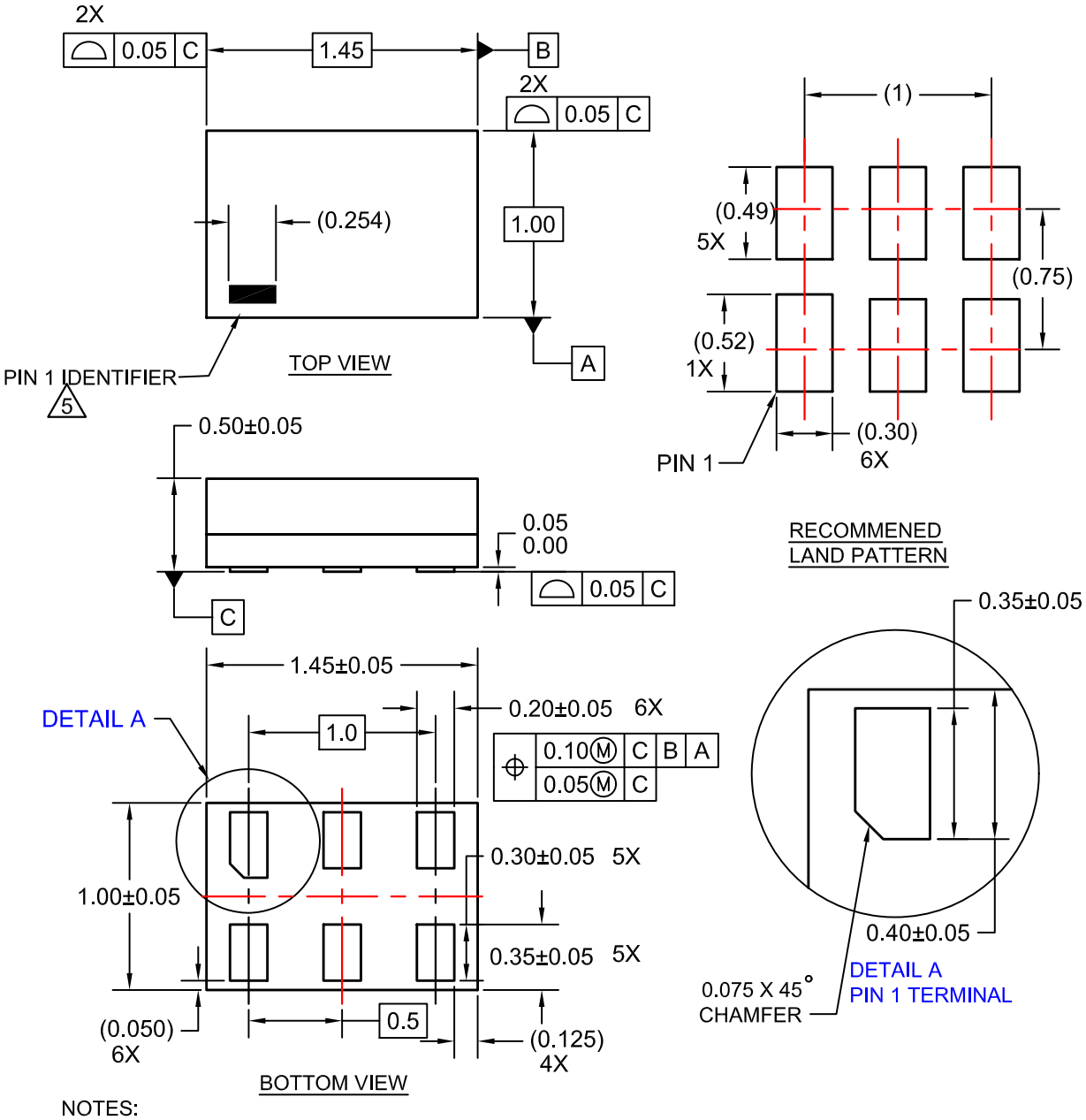
ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping†
NC7WZ07P6X	Z07	SC−88	3000 / Tape & Reel
NC7WZ07L6X	D3	MicroPak	5000 / Tape & Reel
NC7WZ07FHX	D3	MicroPak2	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SIP6 1.45X1.0
CASE 127EB
ISSUE O

DATE 31 AUG 2016



NOTES:

1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-2009
4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

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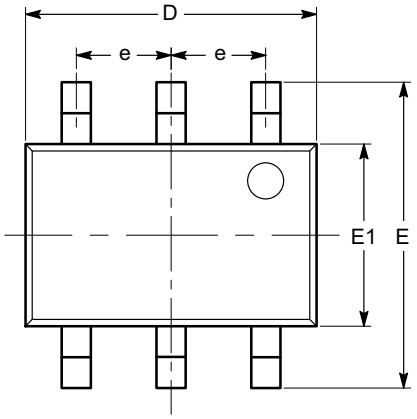
ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM FAIRCHILD MAC06A TO ON SEMICONDUCTOR. REQ. BY B. MARQUIS.	31 AUG 2016

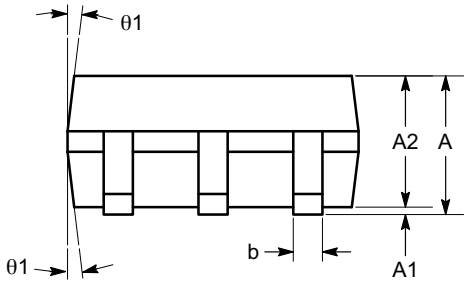
SC−88 (SC−70 6 Lead), 1.25x2
CASE 419AD−01
ISSUE A

DATE 07 JUL 2010

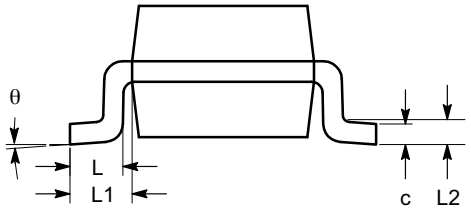


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
L2		0.15 BSC	
θ	0°		8°
θ1	4°		10°



SIDE VIEW



END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-203.

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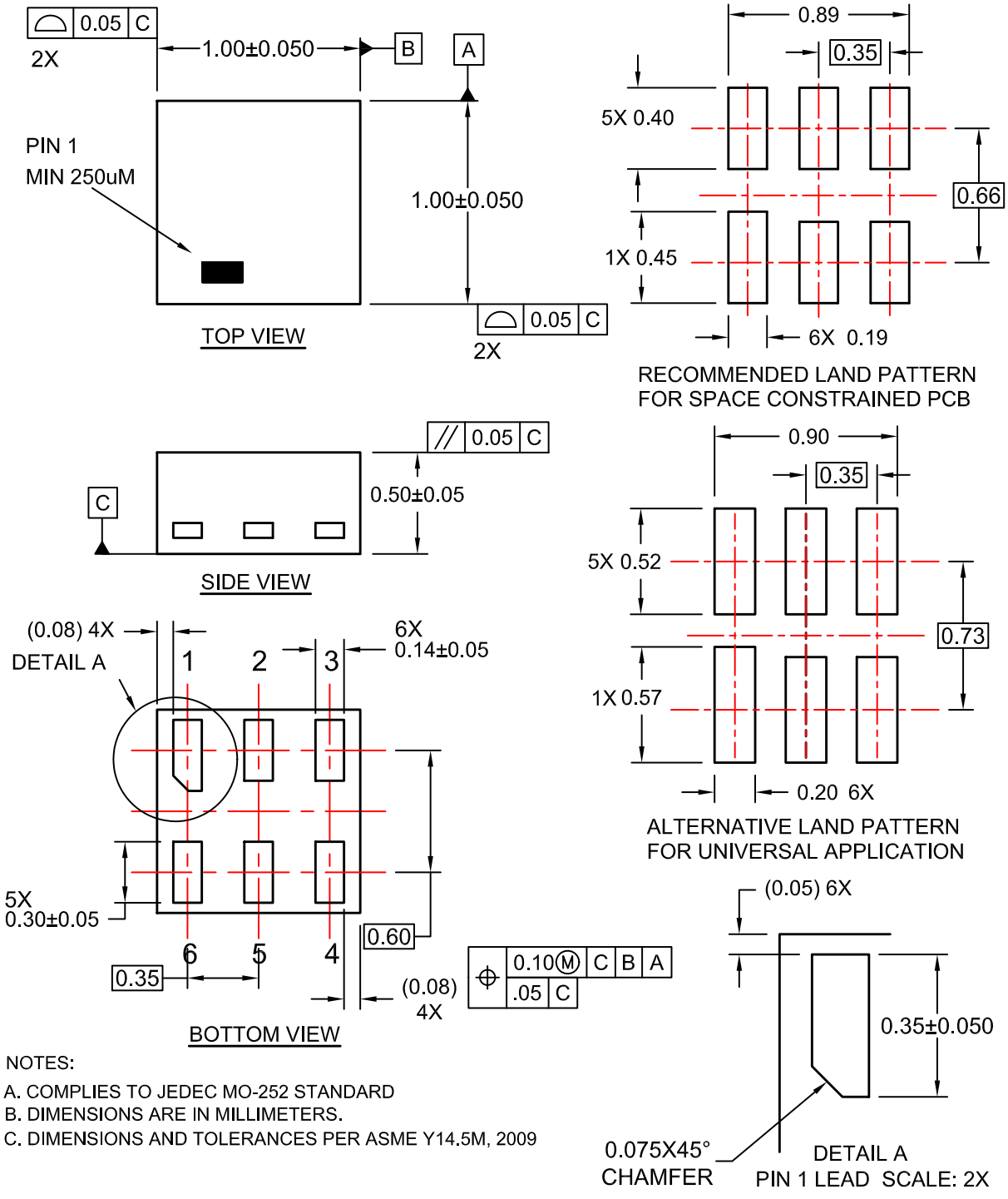
DESCRIPTION:	**SC−88 (SC−70 6 LEAD), 1.25X2**	**PAGE 1 OF 1**

UDFN6 1.0X1.0, 0.35P
CASE 517DP
ISSUE O

DATE 31 AUG 2016



NOTES:

A. COMPLIES TO JEDEC MO-252 STANDARD
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009

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ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM FAIRCHILD MGF06A TO ON SEMICONDUCTOR. REQ. BY B. MARQUIS.	31 AUG 2016

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